

AMENDMENTS TO THE SPECIFICATION

Please amend paragraph [0025] as follows.

[0025] Figure 4 illustrates an apparatus for photoresist recovery in accordance with one embodiment of the invention. System 400, shown in Figure 4, includes a wafer 406 on top of wafer platform 405. The wafer 406 and the wafer platform have been lowered into bowl 420. The motor 430 then rotates the wafer spindle 431 to spin the wafer platform 405 and wafer 406. Excess photoresist is spun off the wafer against the inner surface of bowl 420. At this point a photoresist recovery bowl wash process is effected. The bowl wash uses the same or compatible solvent as is used in the photoresist. A weeping seal 450 dispenses the solvent along the inner surface of the bowl 420. The excess-photoresist/solvent composition proceeds down recovery drainpipe 455 to photoresist recovery container 460. During the photoresist recovery bowl wash, the waste drainpipe 435 is blocked by drainpipe block 436. This prevents the excess-photoresist/solvent composition from proceeding down waste drainpipe 435.